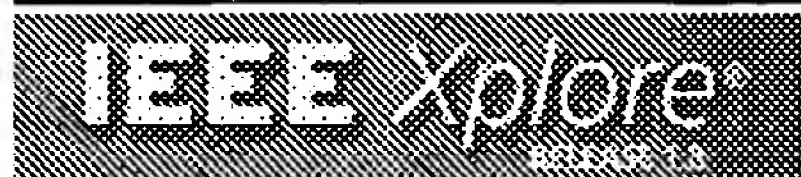


| Ref # | Hits | Search Query                                                                                        | DBs                                                     | Default Operator | Plurals | Time Stamp       |
|-------|------|-----------------------------------------------------------------------------------------------------|---------------------------------------------------------|------------------|---------|------------------|
| L1    | 20   | "5311459"                                                                                           | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/01/25 14:36 |
| L2    | 12   | ((("5311459") or ("6530010") or ("6212618") or ("5600584") or ("6466924") or ("6320619"))).PN.      | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2005/01/25 15:16 |
| L3    | 142  | half adj multiplier\$1                                                                              | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/01/25 15:16 |
| L4    | 67   | complex and 3                                                                                       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/01/25 15:16 |
| L5    | 1    | 4 and despreaders\$1                                                                                | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/01/25 15:16 |
| L6    | 2    | reconfigurable and 4                                                                                | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/01/25 15:18 |
| L7    | 853  | (reconfigurable or re-configurable) and (correlat\$3 or despreaders\$1 or spreaders\$1) and complex | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/01/25 15:29 |
| L8    | 63   | 7 and "708"/\$.ccls.                                                                                | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/01/25 15:28 |
| L9    | 716  | 708/620,422-423.ccls.                                                                               | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/01/25 15:29 |

|     |    |                                              |                                                         |    |    |                  |
|-----|----|----------------------------------------------|---------------------------------------------------------|----|----|------------------|
| L10 | 10 | (reconfigurable or re-configurable)<br>and 9 | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/01/25 15:29 |
| L11 | 5  | 10 not 8                                     | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/01/25 15:29 |

[IEEE HOME](#) | [SEARCH IEEE](#) | [SHOP](#) | [WEB ACCOUNT](#) | [CONTACT IEEE](#)[Membership](#) | [Publications/Services](#) | [Standards](#) | [Conferences](#) | [Careers/Jobs](#)Welcome  
United States Patent and Trademark  
Office[Help](#) | [FAQ](#) | [Terms](#) | [IEEE Peer Review](#)[Quick Links](#)[» Search Results](#)[Welcome to IEEE Xplore](#)

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

[Index of Contents](#)

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

[Search](#)

- ☐ By Author
- ☐ Basic
- ☐ Advanced
- ☐ CrossRef

[Member Services](#)

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library

[Publications](#)

- ☐ Access the IEEE Information File Cabinet

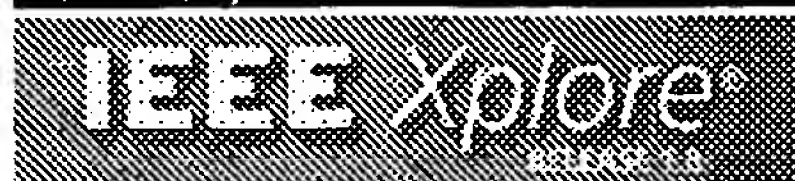
[Print Format](#)Your search matched **0** of **1121826** documents.A maximum of **500** results are displayed, **15** to a page, sorted by **Relevance** in **Descending** order.**Refine This Search:**

You may refine your search by editing the current search expression or entering a new one in the text box.

☐ Check to search within this result set**Results Key:****JNL** = Journal or Magazine   **CNF** = Conference   **STD** = Standard**Results:****No documents matched your query.**[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#) | [Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#) | [No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2004 IEEE — All rights reserved

[IEEE HOME](#) | [SEARCH IEEE](#) | [SHOP](#) | [WEB ACCOUNT](#) | [CONTACT IEEE](#)

[Membership](#) | [Publications/Services](#) | [Standards](#) | [Conferences](#) | [Careers/Jobs](#)


Welcome  
United States Patent and Trademark  
Office


[Help](#) | [FAQ](#) | [Terms](#) | [IEEE Peer Review](#)
[Quick Links](#)
[» Search Results](#)

#### IEEE Xplore

- ☐ Home
- ☐ What Can I Access?
- ☐ Log-out

#### IEEE Xplore

- ☐ Journals & Magazines
- ☐ Conference Proceedings
- ☐ Standards

#### Search

- ☐ By Author
- ☐ Basic
- ☐ Advanced
- ☐ CrossRef

#### Member Services

- ☐ Join IEEE
- ☐ Establish IEEE Web Account
- ☐ Access the IEEE Member Digital Library
- ☐ Renew My IEEE Subscription
- ☐ Renew My IEEE File Cabinet

Print Format

Your search matched **8** of **1121826** documents.

A maximum of **500** results are displayed, **15** to a page, sorted by **Relevance** in **Descending** order.

#### Refine This Search:

You may refine your search by editing the current search expression or entering a new one in the text box.

correlation <and> spreader

☐ Check to search within this result set

#### Results Key:

**JNL** = Journal or Magazine   **CNF** = Conference   **STD** = Standard

#### 1 Parametric studies on temperature drops in bare chip cooling system

Tomimura, T.;

Electronics Packaging Technology Conference, 2002. 4th , 10-12 Dec. 2002

Pages:299 - 303

[\[Abstract\]](#)   [\[PDF Full-Text \(498 KB\)\]](#)   **IEEE CNF**

#### 2 Void-Induced thermal impedance in power semiconductor modules: some transient temperature effects

Katsis, D.C.; van Wyk, J.D.;

Industry Applications, IEEE Transactions on , Volume: 39 , Issue: 5 , Sept.-Oct. 2003

Pages:1239 - 1246

[\[Abstract\]](#)   [\[PDF Full-Text \(1153 KB\)\]](#)   **IEEE JNL**

#### 3 Natural convection enhancement of channel array in conjunction with wall surface

Yazawa, K.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2004.

ITHERM '04. The Ninth Intersociety Conference on , 1-4 June 2004

Pages:128 - 133 Vol.1

[\[Abstract\]](#)   [\[PDF Full-Text \(676 KB\)\]](#)   **IEEE CNF**

#### 4 Thermal management of power electronics modules via acoustic micrography imaging

Haque, S.; Xingsheng Liu; Lu, G.-Q.; Goings, J.;

Applied Power Electronics Conference and Exposition, 2000. APEC 2000.

Fifteenth Annual IEEE , Volume: 1 , 6-10 Feb. 2000

Pages:299 - 305 vol.1

[\[Abstract\]](#)   [\[PDF Full-Text \(952 KB\)\]](#)   **IEEE CNF**

#### 5 A method to predict failure of solder joints caused by thermal shock using finite element analysis for RF power amplifier applications

Yang, M.C.; Cienkus, M.; Hajovsky, M.; Basey, T.;

Thermal and Thermomechanical Phenomena in Electronic Systems, 2000.

ITHERM 2000. The Seventh Intersociety Conference on , Volume: 2 , 23-26

May 2000

Pages:169 - 173 vol. 2

[\[Abstract\]](#) [\[PDF Full-Text \(280 KB\)\]](#) [IEEE CNF](#)

**6 Linear interference suppression for band-limited DS/SS communications with spectral overlapping**

*Joon Ho Cho; Jeong, Y.K.; Lehnert, J.S.;*

MILCOM 2002. Proceedings, Volume: 1, 7-10 Oct. 2002

Pages:743 - 747 vol.1

[\[Abstract\]](#) [\[PDF Full-Text \(601 KB\)\]](#) [IEEE CNF](#)

**7 Experimental measurement and simulation of thermal performance due to aging in power semiconductor devices**

*Katsis, D.C.; van Wyk, J.D.;*

Industry Applications Conference, 2002. 37th IAS Annual Meeting. Conference Record of the, Volume: 3, 13-18 Oct. 2002

Pages:1746 - 1751 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(1152 KB\)\]](#) [IEEE CNF](#)

**8 Void induced thermal impedance in power semiconductor modules: some transient temperature effects**

*Katsis, D.C.; van Wyk, J.D.;*

Industry Applications Conference, 2001. Thirty-Sixth IAS Annual Meeting. Conference Record of the 2001 IEEE, Volume: 3, 30 Sept.-4 Oct. 2001

Pages:1905 - 1911 vol.3

[\[Abstract\]](#) [\[PDF Full-Text \(440 KB\)\]](#) [IEEE CNF](#)

[Home](#) | [Log-out](#) | [Journals](#) | [Conference Proceedings](#) | [Standards](#) | [Search by Author](#) | [Basic Search](#) | [Advanced Search](#) | [Join IEEE](#) | [Web Account](#) | [New this week](#) | [OPAC Linking Information](#) | [Your Feedback](#) | [Technical Support](#) | [Email Alerting](#) | [No Robots Please](#) | [Release Notes](#) | [IEEE Online Publications](#) | [Help](#) | [FAQ](#) | [Terms](#) | [Back to Top](#)

Copyright © 2004 IEEE — All rights reserved